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Precision Glass Processing Supports the Trend Toward Heterogeneous Integration: Laser-Induced Deep Etching (LIDE) for Thin Glass Opens New Perspectives

"With the new LIDE precision process, we are enabling microsystems technology to exploit the full potential of glass," explained Dr. Roman Ostholt, Vice President of LIDE at LPKF, in a presentation at the 3D Systems Summit 2019 in Dresden, Germany. The LIDE process examples ranged from through glass vias to glass embedding and glass capping solutions with vertical walls.

Due to its properties, glass is one of the most interesting materials for advanced IC and wafer level packaging applications. For a long time, glass was very difficult to process. Production-related surface defects have given glass the reputation of being brittle and susceptible to fracture, and therefore glass was, at best, suitable for simple packaging tasks. "Thanks to laser induced deep etching technology (LIDE), it's finally possible to create deep microstructures in glass without causing microcracks, stress or other surface defects; The process is extremely precise and fast. With the use of LIDE-processed glass, even more is possible in heterogeneous integration of advanced IC and wafer level packaging than ever before".

The information from the lecture on the LIDE process and the possibilities it opens up for microsystems technology can be found on the Vitrion web page: www.vitrion.com.

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About LPKF

Established in 1976, LPKF Laser & Electronics manufactures laser systems used in circuit board, microelectronics fabrication and TGV formation. LPKF's worldwide headquarters is located in Hannover, Germany and its North American headquarters resides in Portland, OR.